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Title: **JP2001189378A2: WAFER-CHUCKING HEATING APPARATUS**

Country: **JP Japan**
Kind: **A2 Document Laid open to Public Inspection**

Inventor(s): **ARAI YUSUKE
NOBORI KAZUHIRO
USHIGOE RYUSUKE
UMEMOTO KOUICHI**

Applicant/Assignee: **NGK INSULATORS LTD**
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Application Number: **JP19912000385426**

IPC Class: **H01L 21/68; C23C 16/46; H01L 21/205;**

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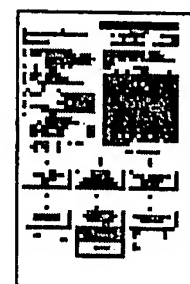
Abstract: **Problem to be solved:** To improve yield, when heating and treating a wafer by preventing a gap from being locally generated at the part between the wafer and a wafer installation surface due to warpage, distortion, or the like of the wafer, when heat-treating the wafer. **Solution:** A resistance electrical heating element 3 is embedded inside a ceramic substrate 2, a film-shaped electrode 5 is formed on one main surface 2a of the ceramic substrate 2, and a ceramic dielectric layer 4 is formed at the side of one main surface 2a, so that the film-shaped electrode 5 can be covered. Coulombic force is generated between a wafer W and the ceramic dielectric layer 4 by a DC power supply 12, the wafer W is attracted to a wafer-attracting surface 6, the resistance electrical heating element 3 is energized for generating heat from the wafer-attracting surface 6, and the attracted wafer W is heated.

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Family: **[Show known family members](#)**

Other Abstract Info: **CHEMABS 119(16)171869V DERABS G1992-219195
JAPABS 170276E000054**

Foreign References: **No patents reference this one**



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